Shenzhen Jianghe New Materials Technology Co.,Ltd

Technical Data Sheet (TDS)

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2120AB-D

Typical Properties

Epoxy Resin 2120AB-D is a transparent flooring compound formulated for curing at both ambient and elevated temperatures. This low-viscosity system features exceptional self-debubbling characteristics and delivers high-clarity, shrinkage-free surfaces.

Applications

Epoxy Resin 2120A-D is specifically engineered for floor surface coating (primer), module potting, mold casting, and electronic component protection including insulation, moisture-proof encapsulation, and secure shielding. It is also suitable for mixing with sand or stone as a paving base material.

Physical & Chemical Properties

Property	Part A: 2120A-D	Part B: 2120B-D
Color	Colorless Transparent	Colorless Transparent
Density (g/cm³)	1.06±0.05	0.95±0.03
Viscosity (mPa•s)	3000±800	50
Brookfield DV2TRV Viscometer	25℃	
Mix Ratio (by Volume)	2 : 1	

Properties of Cured Material

Property	Base + Curing Agent
Physical State	Liquid
Viscosity (mPa•s)	400±200mPa.S
Brookfield DV2TRV Viscometer	25℃
Pot Life (100g mass @ 25°C)	25±5 min
Dosage	280-350 g/m² (varies with substrate)

Processing & Curing Parameters

Hardness (2mm thickness) after 2h @70℃	84D
Hardness (2mm thickness) after 24h @27℃	80D
Hardness (2mm thickness) after 48h @27℃	80-84D

Application Instructions

Working Conditions: Ensure the mixing container is clean. Measure Components A and B strictly by the designated weight ratio. After accurate weighing, stir the mixture thoroughly in a clockwise direction, scraping the inner walls of the container. Allow the mixture to rest for 3-5 minutes before application.

Precautions

1. **Dosage Control:** Prepare the adhesive quantity based on the pot life and application rate to avoid waste.
2. **Low-Temperature Handling:** When the ambient temperature falls below 15°C, preheat Component A to 30°C before mixing to facilitate easier application, as the viscosity increases in cold conditions.
3. **Storage After Use:** The container must be sealed immediately after use to prevent moisture absorption, which can render the product unusable.
4. **High-Humidity Curing:** At relative humidity levels above 85%, the cured surface is prone to absorbing moisture from the air, forming a whitish haze. Therefore, room

temperature curing is not recommended under these conditions; heat-assisted curing is advised.

Test Result

Hardness	Shore D	82±3
Heat Deflection Temperature	℃	70
Water Absorption	%	<0.1

Save

Freeze-Sensitive	Yes	
Moisture-Sensitive	Resin	Curing Agent
	No	Sensitive
Recommended Storage Temperature	15℃ to 25℃ (Must not fall below 10℃ or exceed 50℃.)	
Shelf Life	6 months in original, unopened packaging	
Packaging	Resin	Curing Agent
	5 kg pail	5 kg pail

Note: The performance data provided above are typical values obtained under laboratory conditions of 25°C and 70% relative humidity. They are for reference purposes only.